

Number	Hits	Search Text	DB	Time stamp
-	10	(wayne and renken).in.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/06/04 10:35
-	2	5435646.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/03 07:31
-	4345	(monitor or monitoring or measure or measuring or record or recording) with (process or processing) with (condition) and temperature and pressure	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/03 07:34
-	1177	(monitor or monitoring or measure or measuring or record or recording) with (process or processing) with (condition) and temperature and pressure and (semi-conductor or semiconductor)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/03 07:35
-	822	(monitor or monitoring or measure or measuring or record or recording) with (process or processing) with (condition) and temperature and pressure and (semi-conductor or semiconductor) and substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/06/04 10:23
-	319	(monitor or monitoring or measure or measuring or record or recording) with (process or processing) near3 (condition) and temperature and pressure and (semi-conductor or semiconductor) and substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/03 07:37
-	190	(monitor or monitoring or measure or measuring or record or recording) with (process or processing) near3 (condition) and temperature and pressure and (semi-conductor or semiconductor) and substrate	USPAT	2003/06/04 07:32
-	13	(particle and counter and (evaluate or evaluated or evaluating or calibrate or calibrated or calibrating)).ab.	USPAT	2003/04/03 09:19
-	0	5686650.URPN.	USPAT	2003/04/03 09:22
-	4	("3654551" "4434647" "5407269" "5456102").PN.	USPAT	2003/04/03 09:22
-	94	(particle and counter and (evaluate or evaluated or evaluating or calibrate or calibrated or calibrating)).ab.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/03 09:24
-	220	(susumu and sakata).in.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/03 09:24
-	16	(susumu and sakata).in. and particle	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/03 09:24
-	106	PCMD	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/06/03 09:34
-	49035	(semiconductor or semi-conductor) and substrate and (process or processing) with (control or controlling or controller or controlled)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/06/03 09:53
-	84	(semiconductor or semi-conductor) and substrate and (process or processing) with (control or controlling or controller or controlled) and leg and shelf and sensor	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/06/03 10:27

	22	("4437772" "4448547" "4569570" "4576486" "4626110" "4916497" "4986671" "4988212" "5087124" "5183338" "5299869" "5381231" "5393371" "5436494" "5470155" "5489988" "5746513" "5775808" "5830277" "5876119" "5967661" "5969639"). PN.	USPAT	2003/06/03 10:21
-	2	("Re32369" "5262944"). PN.	USPAT	2003/06/03 10:24
-	4	("4063095" "5310260" "5660472" "5830277"). PN.	USPAT	2003/06/03 10:25
-	39	(semiconductor or semi-conductor) and substrate and (process or processing) with (control or controlling or controller or controlled) and (leg or spacer) with (shelf or platform) and sensor	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/06/03 10:34
-	24	"5444637"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/06/03 10:34
-	2	5444637.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/06/03 10:35
-	21	5444637.URPN.	USPAT	2003/06/04 10:36
-	6	("4079508" "4745564" "4890245" "4945769" "4971921" "5142331"). PN.	USPAT	2003/06/03 10:46
-	1	6075909.pn.	USPAT	2003/06/03 10:52
-	0	6075909.URPN.	USPAT	2003/06/03 10:48
-	6	("4659220" "5414504" "5465154" "5786886" "5946082" "5969639"). PN.	USPAT	2003/06/04 10:00
-	1	5969639.pn.	USPAT	2003/06/03 12:01
-	334	"73/866.1".ccls.	USPAT	2003/06/03 12:01
-	4	"73/866.1".ccls. and wafer	USPAT	2003/06/03 12:02
-	1	"73/866.1".ccls. and platform with (leg or spacer)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/06/03 12:02
-	2	("Re32369" "5262944"). PN.	USPAT	2003/06/03 12:03
-	5	5969639.URPN.	USPAT	2003/06/03 12:03
-	4	circuit with platform with (leg or spacer) same sensor	USPAT	2003/06/03 12:38
-	6	sensor with circuit with elevated with surface	USPAT	2003/06/03 12:42
-	176	sensor with circuit with spaced with surface	USPAT	2003/06/03 12:57
-	16	((temperature or thermal) near2 sensor or thermocouple) with circuit with spaced with surface	USPAT	2003/06/03 12:48
-	6	("5008541" "5448068" "5486698" "5512748" "5602043" "5684302"). PN.	USPAT	2003/06/03 12:49
-	793	circuit with spaced with surface with substrate	USPAT	2003/06/03 13:07
-	24	circuit with spaced with surface with substrate and ((temperature or thermal) near2 sensor or thermocouple)	USPAT	2003/06/03 13:01
-	432	circuit with (spacer or post or leg) with surface with substrate	USPAT	2003/06/03 13:44
-	43	circuit with (spacer or post or leg) with surface with wafer	USPAT	2003/06/03 14:01
-	5	module with (spacer or post or leg) with surface with wafer	USPAT	2003/06/03 15:19
-	321	"438/18".ccls.	USPAT	2003/06/03 15:42
-	17	"438/18".ccls. and temperature.ab.	USPAT	2003/06/04 10:20
-	53	"438/17".ccls. and temperature.ab.	USPAT	2003/06/03 15:52
-	60	("156/345.24" or "156/345.26" or "156/345.27" or "156/345.28").ccls. and temperature.ab.	USPAT	2003/06/04 09:54

	4	(monitor or monitoring or measure or measuring or record or recording) with (process or processing) near3 (condition) and temperature and pressure and (LCD with glass) and substrate	USPAT	2003/06/04 12:18
	4	(monitor or monitoring or measure or measuring or record or recording) with (process or processing) near3 (condition) and temperature and pressure and (LCD with glass)	USPAT	2003/06/04 07:35
	1135	("156/345.24" or "156/345.26" or "156/345.27" or "156/345.28" or "438/18" or "438/17").cccls.	USPAT	2003/06/04 09:55
	12	("156/345.24" or "156/345.26" or "156/345.27" or "156/345.28" or "438/18" or "438/17").cccls. and (induction or inductive) near4 power near4 (source or supply)	USPAT	2003/06/04 09:56
	5	("4659220" "5414504" "5465154" "5786886" "5946082" "5969639").PN. and power	USPAT	2003/06/04 10:00
	124	(438/18 or 438/17).cccls. and mass	USPAT	2003/06/04 10:20
	5	(438/18 or 438/17).cccls. and (equal or equivalent) with mass	USPAT	2003/06/04 10:22
	16	(monitor or monitoring or measure or measuring or record or recording) with (process or processing) with (condition) and temperature and pressure and (semi-conductor or semiconductor) and substrate and (equal or equivalent) with mass	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/06/04 10:25
	1	5444637.URPN. and cavity	USPAT	2003/06/04 10:36
	6	(monitor or monitoring or measure or measuring or record or recording) with (process or processing) near3 (condition) and (LCD with glass) with substrate	USPAT	2003/06/04 12:20